

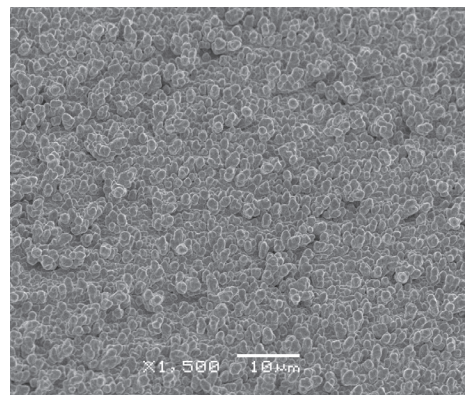
Low profile, reverse treat, electrodeposited copper foil.

Applications:

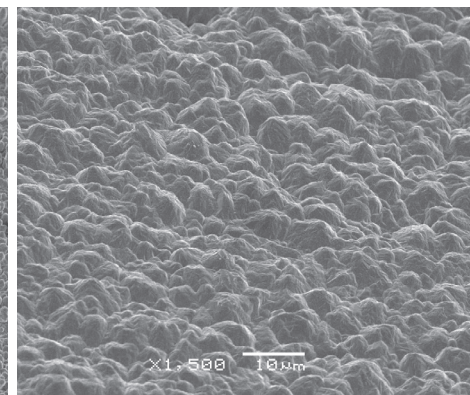
- PCB inner layers

Features:

- IPC Grade III
- Treatment on drum side of foil
- Excellent adhesion to a wide range of resin systems
- Arsenic free



Treated Drum Side
H oz. /18 µm (1500x)



Untreated Matte Side
H oz. /18 µm (1500x)

Typical Values:

Attribute		Unit	Value			Reference
Thickness Designation			H	1	2	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		µm	18	35	70	
		oz.	1/2	1	2	
Area Weight		g/m ²	152.5	305	610	
		g/254 in ²	25	50	100	
		oz./ft ²	0.5	1	2	
Roughness	Drum Side Ra	µm	4.1			IPC-TM-650-2.2.17
		µ"	160			
	Matte Side Rz	µm	4.5	5.7	8.9	
		µ"	175	225	350	
Tensile	Ambient	Kg/mm ²	42.2	38.7	36.9	IPC-TM-650-2.4.18
		Kpsi	60	55	53	
	180°C	Kg/mm ²	21			
		Kpsi	30			
Elongation	Ambient	%	8	15	20	
	180°C	%	8			
Peel Strength* (Drum/Treated Side)	Cond. B	Kg/cm	>0.71	>0.80	>0.89	IPC-TM-650-2.4.8
		Lbs/in	>4.0	>4.5	>5.0	

* Peel strength measured on 170°C Tg Epoxy

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